

Shenzhen Zhuo Lian micro technology Co., LTD

# **JTW2G44AN1608T80R**

**Multilayer Chip Antenna**

**For 2.44GHz Wireless Communication**

## Features

- ※ Monolithic SMD with small, low-profile and light-weight type.
- ※ Wide bandwidth
- ※ RoHS compliant

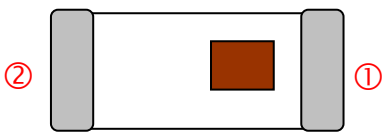
## Applications

2400~2500MHz ISM Band Systems

## Specifications

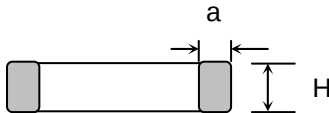
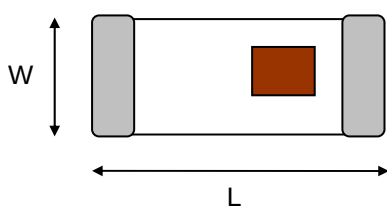
|                       |                          |
|-----------------------|--------------------------|
| Center frequency      | 2.44GHz                  |
| Bandwidth             | 80MHz(typ.)              |
| Peak gain             | 0.5dBi(typ.) (YZ-total)  |
| Average Gain          | -2.0dBi(typ.) (YZ-total) |
| VSWR                  | 3(max)                   |
| Impedance             | 50Ω                      |
| Power Capacity        | 3W(max)                  |
| Operation temperature | -40 ~ +85 °C             |
| Storage temperature   | -40 ~ +85 °C             |

Terminal Configuration



| Pin No.        | 1             | 2  |
|----------------|---------------|----|
| Pin assignment | Feeding Point | NC |

Dimensions and Recommended PC Board Pattern

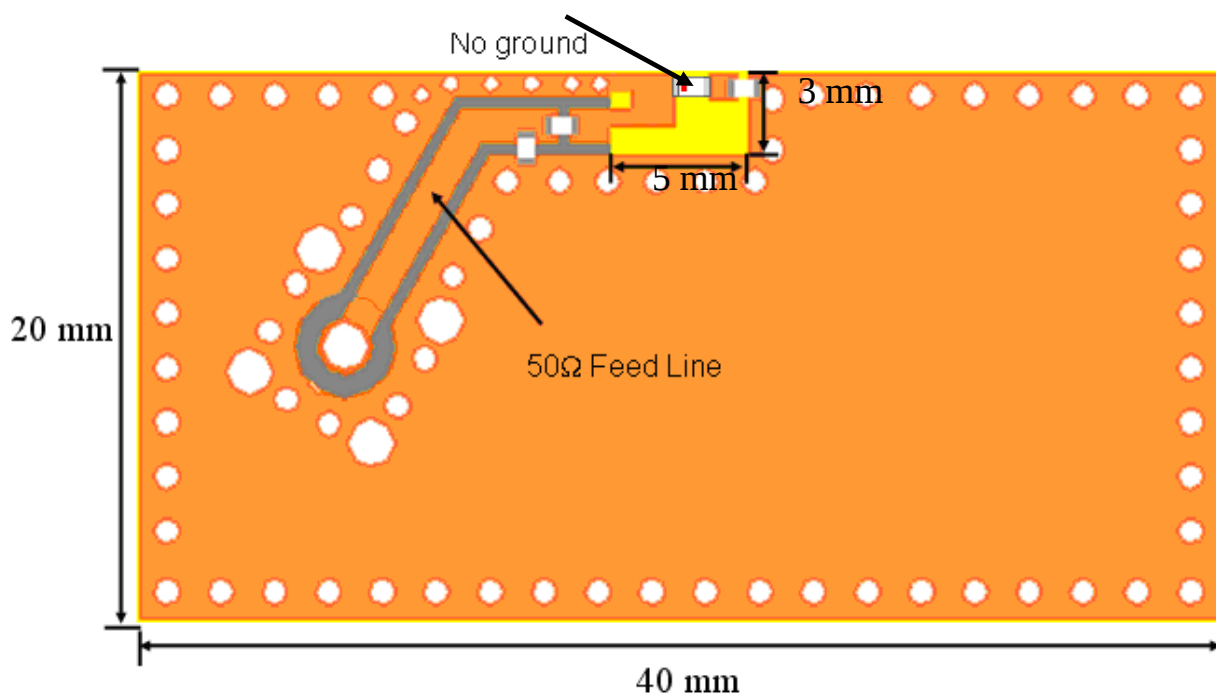


Unit : mm

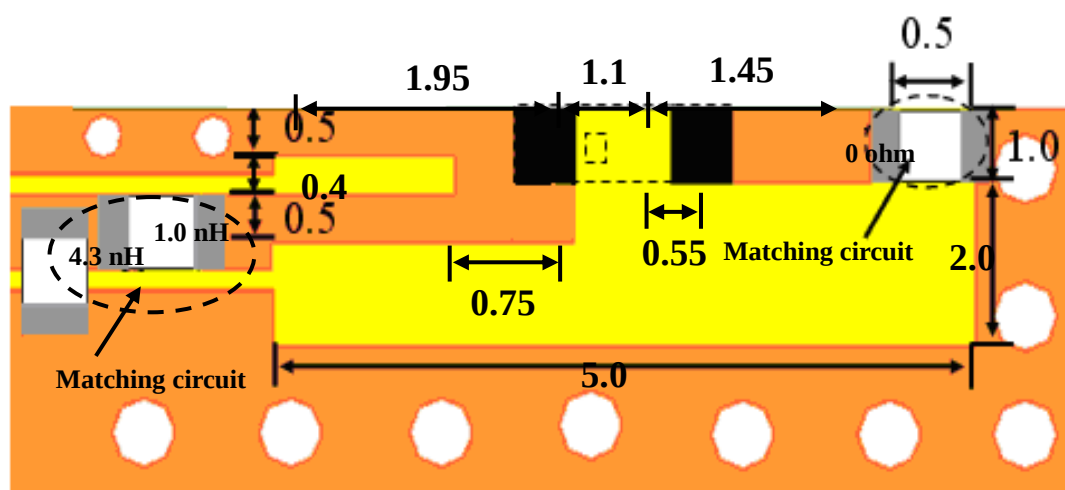
| Symbol         | L       | W       | H        | a        |
|----------------|---------|---------|----------|----------|
| Dimensions(mm) | 1.6±0.1 | 0.8±0.1 | 0.4± 0.1 | 0.25±0.1 |

## Typical Electrical Characteristics (T=25oC)

### ※Test Board



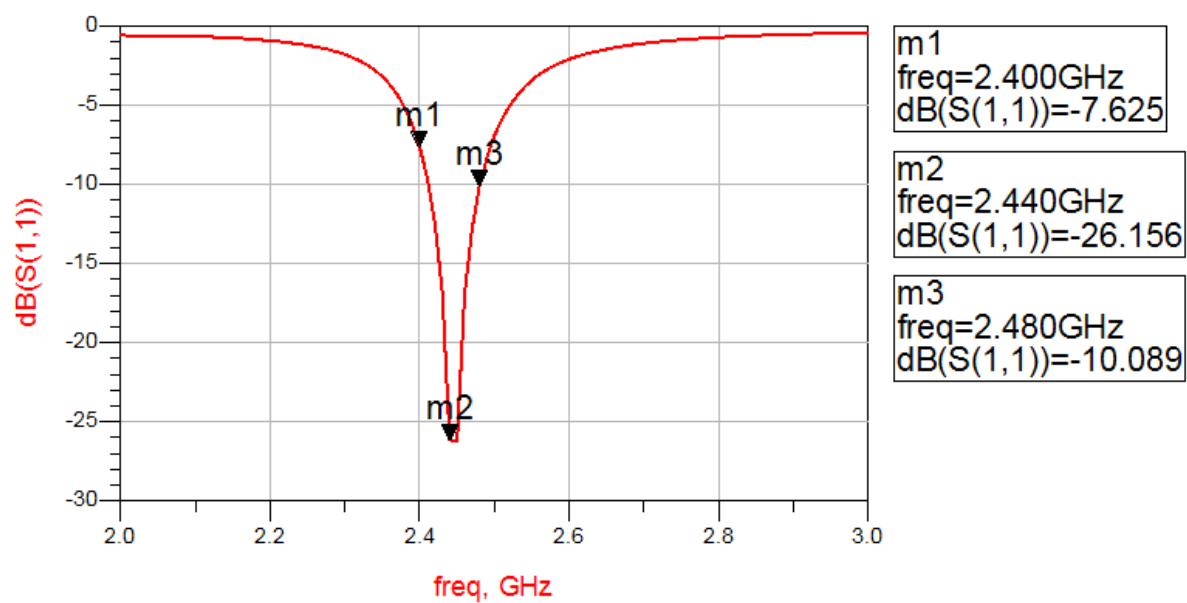
### ※Antenna Footprint with matching (Unit : mm)



(Matching circuit and component values will be different, depending on PCB layout)

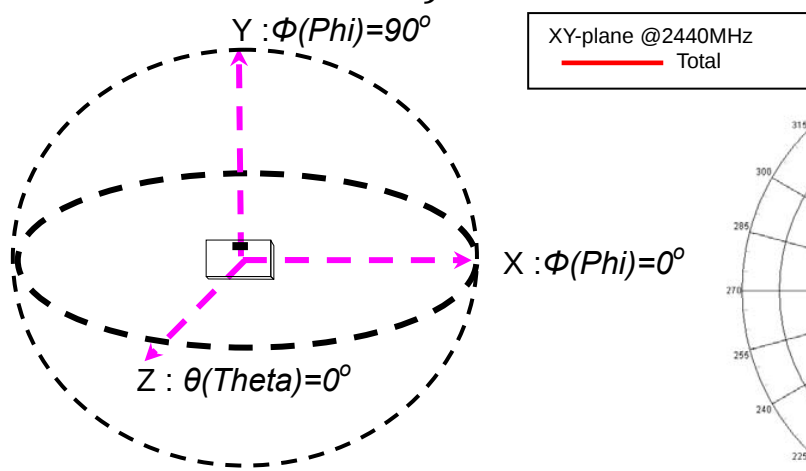
\*Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

## ※Return Loss with matching Circuits

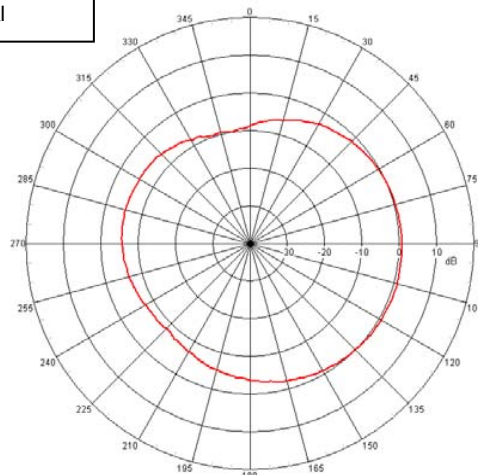


# ※Radiation Patterns@ 2.44 GHz

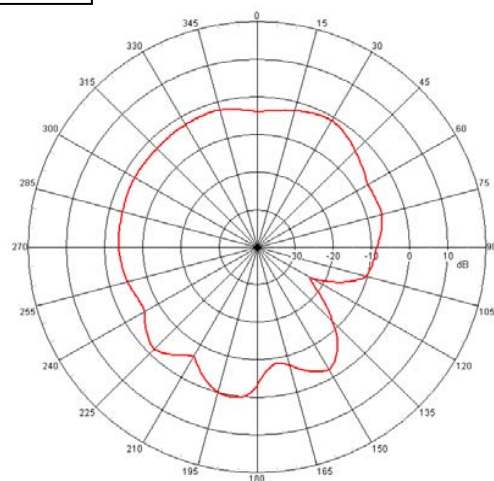
(Antenna Efficiency 38 % @ 2.4 GHz ; 49 % @ 2.44 GHz ; 44 % @ 2.48 GHz)



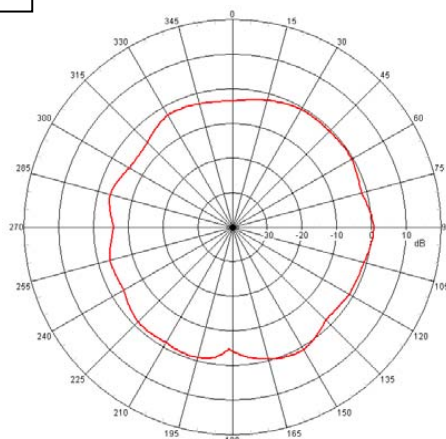
XY-plane @2440MHz  
— Total



XZ-plane @2440MHz  
— Total

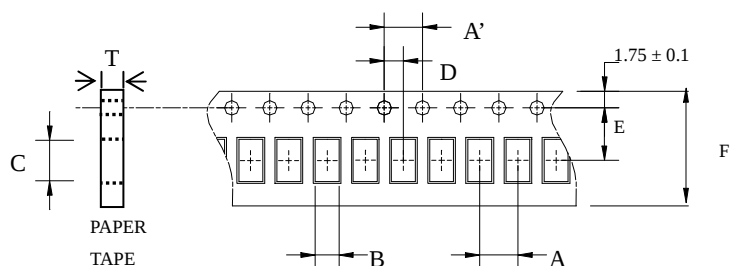


YZ-plane @2440MHz  
— Total



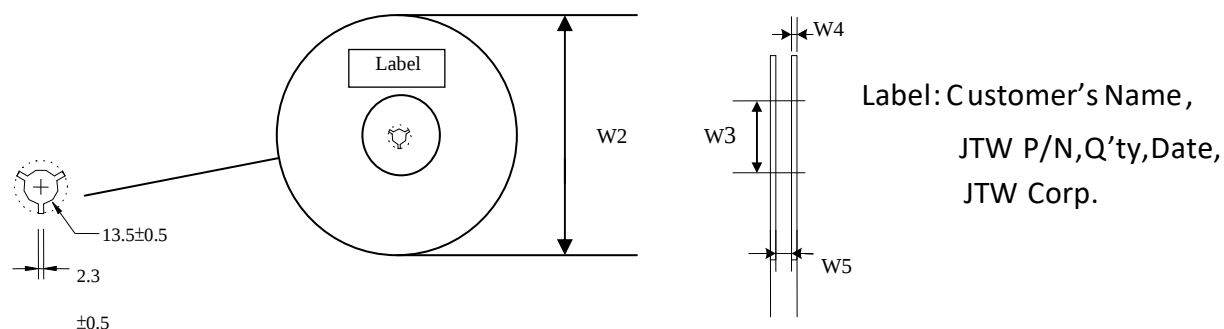
# Taping Specifications

※Tape & Reel Dimensions (Unit: mm)



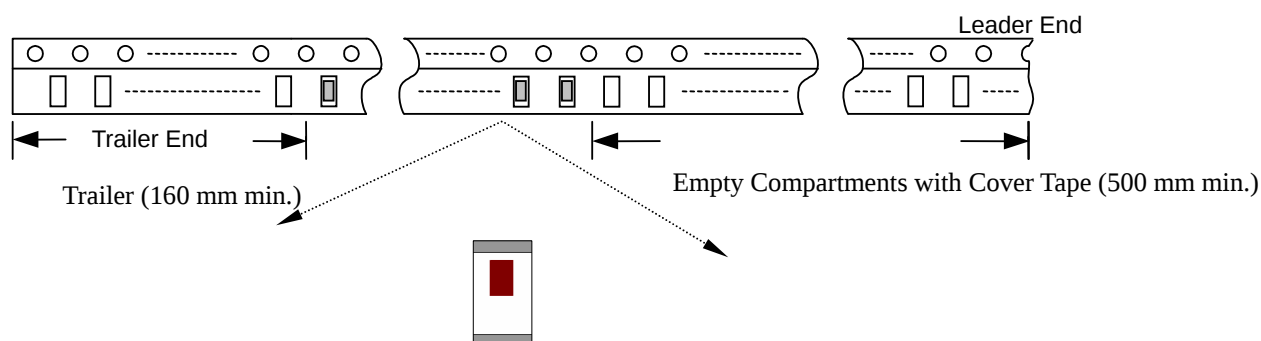
| Type | A         | A'        | B          | C         | D          | E         | F         | T         | Quantity/per reel | Tape material |
|------|-----------|-----------|------------|-----------|------------|-----------|-----------|-----------|-------------------|---------------|
| 1608 | 4.0 ± 0.1 | 4.0 ± 0.1 | 0.95 ± 0.1 | 1.8 ± 0.1 | 2.0 ± 0.05 | 3.5 ± 0.1 | 8.0 ± 0.1 | 0.6 ± 0.1 | 4000pcs           | Paper         |

※Reel Dimensions (Unit: mm)

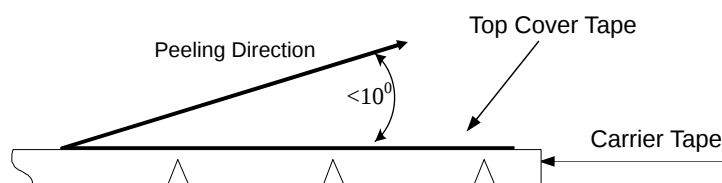


| Type | W2      | W3     | W4        | W5        |
|------|---------|--------|-----------|-----------|
| 1608 | 178 ± 1 | 60 ± 1 | 1.4 ± 0.2 | 9.0 ± 0.3 |

## ※Leader and Trailer Tape



## ※Peel-off Force



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of  $300 \pm 10$  mm/min .

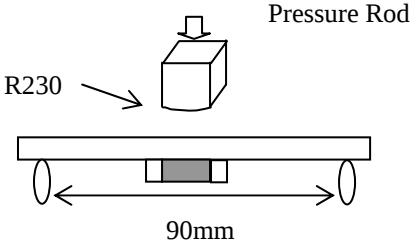
## ※Storage Conditions

- (1) Temperature: 5 ~35 °C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

## Notes

※The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

## Mechanical & Environmental Characteristics

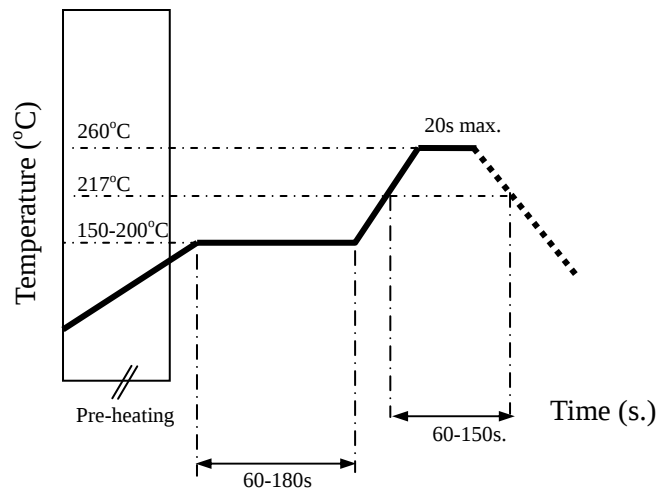
| Item                                            | Requirements                                                                                                                                                 | Procedure                                                                                                                                                                                                                                                                        |
|-------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Solderability                                   | <ol style="list-style-type: none"> <li>1. No apparent damage</li> <li>2. More than 95% of the terminal electrode shall be covered with new solder</li> </ol> | <ol style="list-style-type: none"> <li>1. Preheat: <math>120 \pm 5^{\circ}\text{C}</math></li> <li>2. Solder: <math>245 \pm 5^{\circ}\text{C}</math> for <math>5 \pm 1</math> sec</li> </ol>                                                                                     |
| Soldering strength<br>(Termination<br>Adhesion) | <ol style="list-style-type: none"> <li>1. 10N minimum</li> </ol>                                                                                             | <ol style="list-style-type: none"> <li>1. Solder specimen onto test jig.</li> <li>2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken.<br/><br/>Pushing force is applied to longitude direction</li> </ol>                                  |
| Deflection<br>(Substrate<br>Bending)            | <ol style="list-style-type: none"> <li>1. No apparent damage</li> </ol>                                                                                      | <ol style="list-style-type: none"> <li>1. Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile.</li> <li>2. Apply a bending force of 2mm deflection</li> </ol>  |

|                                         |                                                                                   |                                                                                                                                                                  |
|-----------------------------------------|-----------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Heat/Humidity<br>Resistance             | 1. No apparent damage<br>2. Fulfill the electrical<br>specification<br>after test | 1. Temperature: $85 \pm 2^{\circ}\text{C}$<br>2. Humidity: 90% ~ 95% RH<br>3. Duration: 1000±48hrs<br>4. Recovery: 1-2hrs                                        |
| Thermal shock<br>(Temperature<br>Cycle) | 1. No apparent damage<br>2. Fulfill the electrical<br>specification after test    | 1. One cycle/step 1: $125 \pm 5^{\circ}\text{C}$<br>for 30 min<br>step 2: $-40 \pm 5^{\circ}\text{C}$ for 30 min<br>2. No of cycles: 100<br>3. Recovery: 1-2 hrs |
| Low Temperature<br>Resistance           | 1. No apparent damage<br>2. Fulfill the electrical<br>specification after test    | 1. Temperature: $-40 \pm 5^{\circ}\text{C}$<br>2. Duration: 500 ±24hrs<br>3. Recovery: 1-2hrs                                                                    |

# Soldering Conditions

※ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



## Notes

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## Reminders for users of JTW ceramic chip antennas

1. This chip antenna is made of ceramic materials which are relatively more rigid and brittle compared to printed circuit board materials. Bending of circuit board at the locations where chip antenna is mounted may cause the cracking of solder joints or antenna itself.
2. Punching/cutting of the break-off tab of PCB panel may cause severe bending of the circuit board which may result in cracking of solder joints or chip antenna itself. Therefore break-off tab shall be located away from the installation site of chip antenna.
3. Be cautious when ultrasonic welding process needs to be used near the locations where chip antennas are installed. Strong ultrasonic vibration may cause the cracking of chip antenna solder joints.  
Presented data were measured on reference PCB (ground) as shown in this specification. When the antenna placement or size of the PCB is changed, antenna performance and values of matching components may differ from data shown here.
4. Information presented in this Reference Specification is believed to be correct as of the date of publishing. JointWel Technologies Corporation reserves the rights to change the Reference Specification without notice due to technical improvements, etc. Please consult with JointWel's engineering team about the latest information before using this product. Per request, we may provide advice and assistance in implementing this antenna to a customer's device by simulation or real measurement of the interested device in our testing facilities.